

## ABSTRACT

The object was to provide a sheet for forming a protective film, with which a short circuit between fine-pitched bumps can be prevented. And the object was solved by providing a sheet for forming a protective film, the sheet having a laminated structure of  
5 a curable resin film (x) and a support sheet (Y), wherein the sheet for forming a protective film is to be used to form a protective film (X) on a bump-formed surface of a semiconductor wafer having a plurality of bumps and satisfying a certain requirement indicating that the semiconductor wafer has fine-pitched bumps; and the sheet for forming a protective film satisfies a certain requirement specified by a modulus of  
10 elasticity in tension  $E'$ .

Selected Drawing: Fig. 1